

Features

- Output: 28 ... 30 V/500 mA
- High-power trunk for high device count and long cable lengths
- With galvanic isolation
- Installation in Zone 2/Class I, Div. 2
- For FOUNDATION Fieldbus H1 and PROFIBUS PA
- High efficiency, low heat dissipation for high packing density
- Hot swappable in redundant configuration
- Module exchange without tools during operation

Function

This Power Supply Module is a system component for the FieldConnex® Power Hub and can be plugged into the motherboard. It adapts current and voltage for the supply of fieldbus segments and field devices.

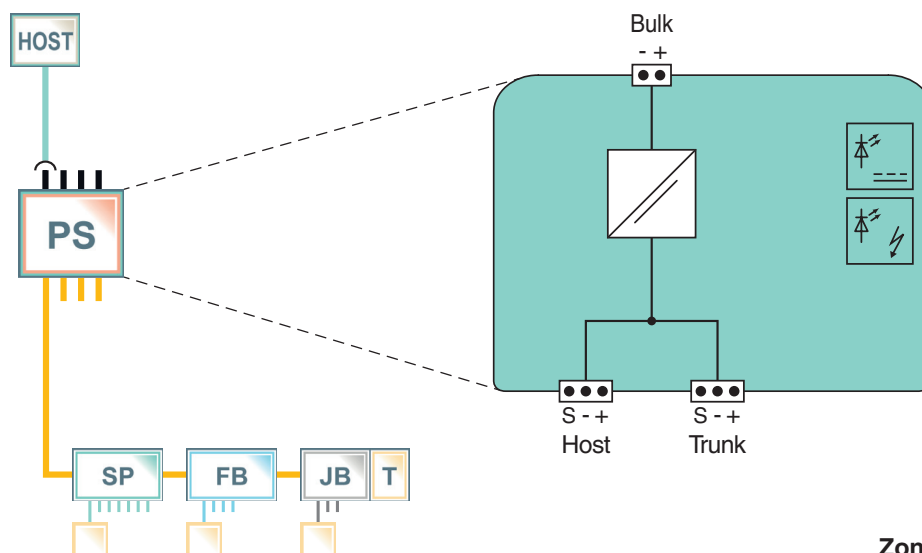
This power supply features the highest output power and allows for maximum cable lengths and highest number of devices in hazardous areas with the High-Power Trunk concept.

Reliability of communication is enhanced through galvanic isolation between segment and bulk power supply. Two LEDs indicate power and status. In redundant configuration two modules are connected in parallel via simple circuits ensuring seamless operation.

Assembly



Connection



Zone 2/Div. 2

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Refer to "General Notes Relating to Pepperl+Fuchs Product Information".

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General specifications		
Design / Mounting		Motherboard based
Supply		
Rated voltage	U_n	19.2 ... 35 V DC
Rated current	I_n	910 ... 490 mA
Power dissipation		typ. 1.8 W
Fieldbus interface		
Rated voltage	U_N	28 ... 30 V
Rated current	I_N	500 ... 10 mA
Short-circuit current		550 mA
Terminating impedance		motherboard specific
Indicators/operating means		
LED ERR		red flashing: short-circuit or undervoltage at output
LED PWR		green if $U_{out} > 28$ V
Electrical isolation		
Fieldbus segment/Supply		functional insulation acc. to IEC 62103, rated insulation voltage 250 V AC
Directive conformity		
Electromagnetic compatibility		
Directive 2014/30/EU		EN 61326-1:2013
Standard conformity		
Electromagnetic compatibility		NE 21:2011
Degree of protection		IEC 60529
Fieldbus standard		IEC 61158-2
Shock resistance		EN 60068-2-27
Vibration resistance		EN 60068-2-6
Ambient conditions		
Ambient temperature		-40 ... 70 °C (-40 ... 158 °F)
Storage temperature		-40 ... 85 °C (-40 ... 185 °F)
Relative humidity		< 95 % non-condensing
Shock resistance		15 g 11 ms
Vibration resistance		1 g, 10 ... 150 Hz
Pollution degree		max. 2, according to IEC 60664
Corrosion resistance		acc. to ISA-S71.04-1985, severity level G3
Mechanical specifications		
Connection type		motherboard specific
Core cross-section		motherboard specific
Housing material		Polycarbonate
Housing width		18 mm
Housing height		106 mm
Housing depth		128 mm
Degree of protection		IP20
Mass		approx. 150 g
Mounting		motherboard mounting
Data for application in connection with Ex-areas		
Outputs		
Voltage	U_o	32 V
Statement of conformity		TÜV 04 ATEX 2500 X
Group, category, type of protection, temperature class		 II 3 G Ex nA IIC T4 Gc
Directive conformity		
Directive 2014/34/EU		EN 60079-0:2012 , EN 60079-11:2012 , EN 60079-15:2010
International approvals		
FM approval		CoC 3024816, CoC 3024816C
Approved for		Class I, Division 2, Groups A, B, C, D, T4 / Class I, Zone 2, AEx/Ex nA IIC T4
IECEX approval		IECEX TUN 13.0038X
Approved for		Ex nA IIC T4 Gc
Certificates and approvals		
Marine approval		pending
General information		
Supplementary information		Statement of Conformity, Declaration of Conformity, Attestation of Conformity and instructions have to be observed where applicable. For information see www.pepperl-fuchs.com .

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